

**Features**

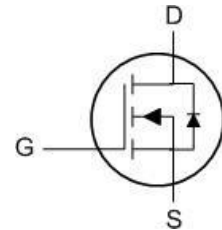
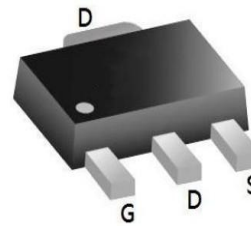
- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$


**Product Summary**

BVDSS	RDSON	ID
100V	110mΩ	6.5 A

**Applications**

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

**GCH, - ! @Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	6.5	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	3.2	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	12	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>3</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

**Thermal Data**

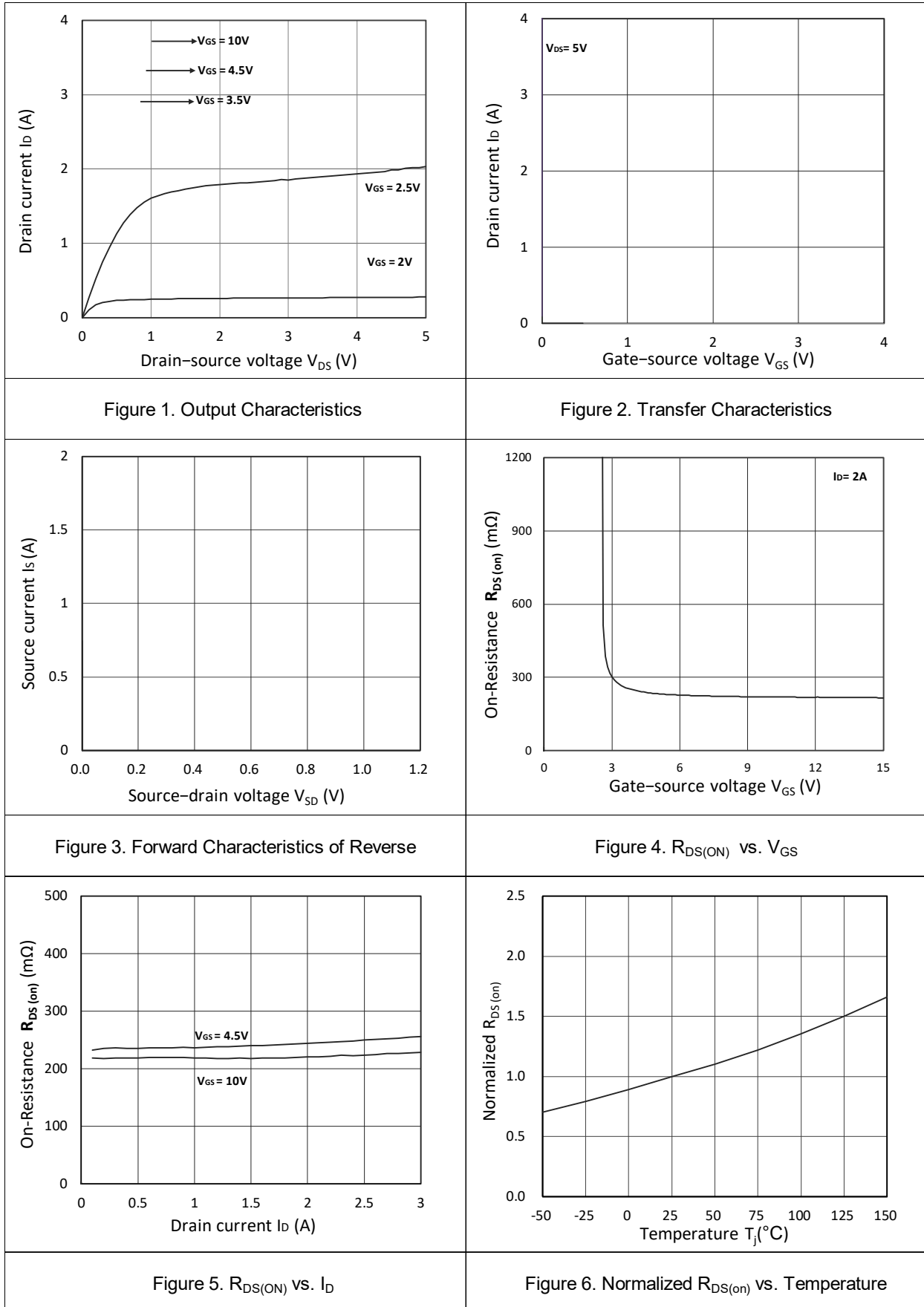
Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	125	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	80	$^\circ C/W$

**Electrical Characteristics**  $T_C=25^{\circ}\text{C}$  unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	100	110	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>note3</sup>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.95	3.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance <sup>note2</sup>	$V_{GS} = 10V, I_D = 3A$	-	110	140	m $\Omega$
<b>Dynamic Characteristics</b> <sup>note4</sup>						
$C_{iss}$	Input Capacitance	$V_{DS} = 50V, V_{GS} = 0V,$ $f = 1.0MHz$	-	206	-	pF
$C_{oss}$	Output Capacitance		-	28.9	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	1.4	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = 50V, I_D = 3A,$ $V_{GS} = 10V$	-	4.3	-	nC
$Q_{gs}$	Gate-Source Charge		-	1.5	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	1.1	-	nC
<b>Switching Characteristics</b> <sup>note4</sup>						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 50V, I_{DS}=3A$ $R_G = 2\Omega, V_{GEN} = 10V$	-	14.7	-	ns
$t_r$	Turn-On Rise Time		-	3.5	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	20.9	-	ns
$t_f$	Turn-Off Fall Time		-	2.7	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current <sup>note2</sup>		-	-	6.5	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	12	A
$V_{SD}$	Drain to Source Diode Forward Voltage <sup>note3</sup>	$V_{GS} = 0V, I_S = 3A$	-	-	1.3	V
$t_{rr}$	Body Diode Reverse Recovery Time	$V_{GS} = 0V, I_F = 3A,$ $di/dt = 100A/\mu s$	-	32.1	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Time Charge		-	39.4	-	nC
$I_{rrm}$	Peak Reverse Recovery Current		-	2.1	-	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5.  $V_{DD}=50$  V,  $R_G=50$   $\Omega$ ,  $L=0.3$  mH, starting  $T_j=25$   $^{\circ}\text{C}$

**Typical Characteristics**


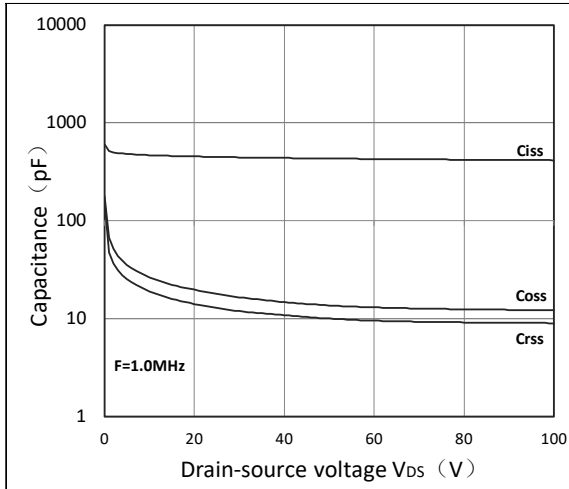


Figure 7. Capacitance Characteristics

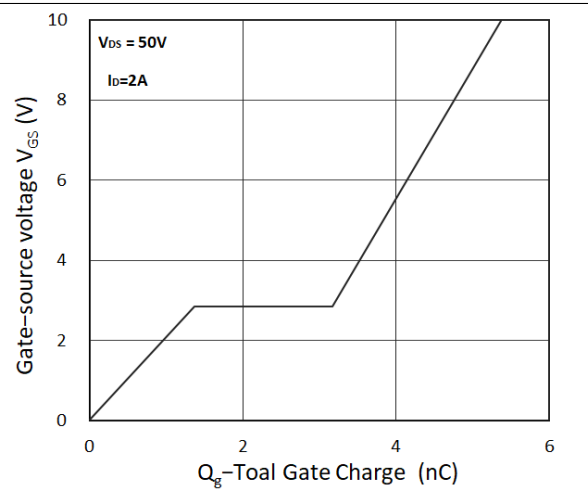
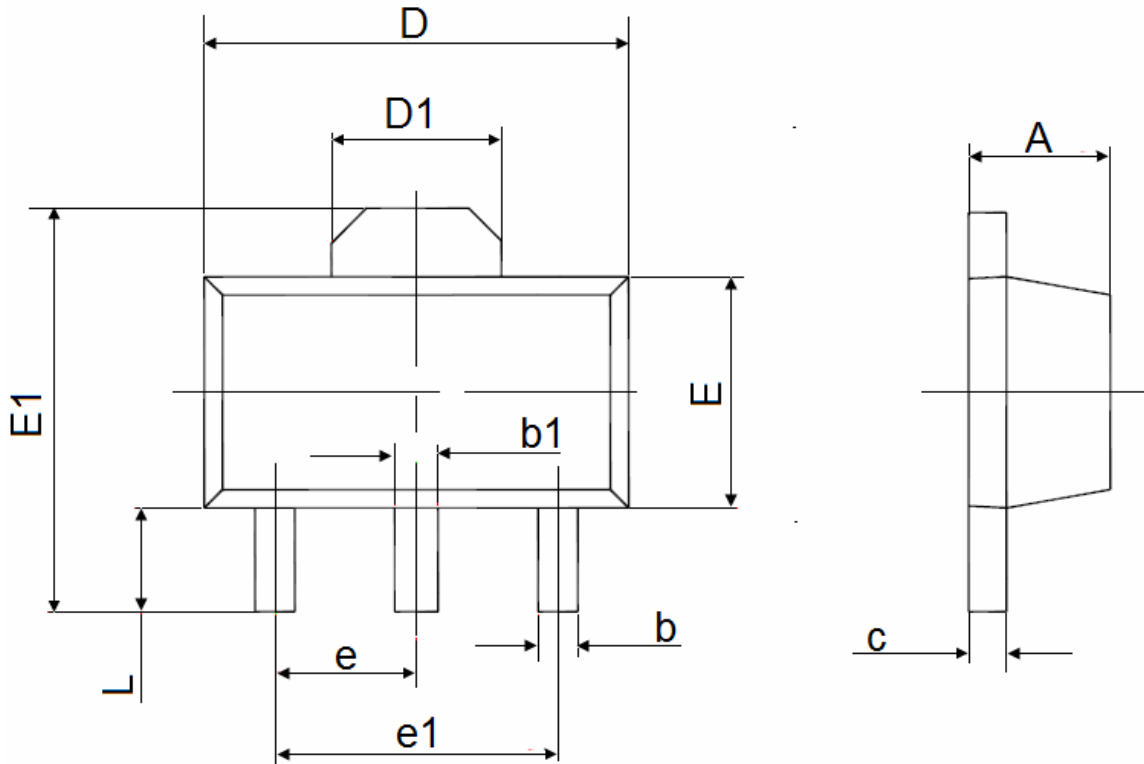


Figure 8. Gate Charge Characteristics

**SOT-89-3L Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047